

PRINTED CIRCUIT BOARD FABRICATION NOTES

Efficient Power Conversion
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Printed Circuit board fabrication instructions, unless otherwise specified:

1. Any changes to the design must be approved by EPC in writing.
2. Fabricate using Gerber artwork. Do not add any text, logos, etc. to the top side of the board.
3. Acceptability of PCB Fabrication, except as specified in this drawing, must comply to IPC-6012E, class 2.
Complete array flatness must be within 7.5 mil per inch
4. Material, Copper Clad Laminate sheet in accordance with IPC-4101.
Material: Use FR370-HR Substrate or similar. Must have the following Properties:
 - a. Tg(min) = 180 degrees C
 - b. Td(min) = 340 degrees C
 - c. Flame rating 94V0
 - d. Dielectric = 4.0/5.0Layer to layer registration to be within 0.003 inches unless specified differently.
5. All holes to be located by pad centers
All PTH holes to be Copper (Cu) Plated thru per IPC-2221, 0.000787 inches min. thickness and be within .003 inches dia. of true position
All NPTH hole be within .002 inches dia. of true position
6. All vias (0.010 inches hole and smaller) to be covered with soldermask (tented) on both sides of the board per Gerber and follow IPC4761 type VII via (filled (non conductive) and plated over).
7. Solder mask created 1:1, do not enlarge or modify.
Do not clip solder mask.
Solder Mask over bare Copper, both sides, using Taiyu 4000HFX L.P.I or PSR-2000/ LF02/CA-25 or equiv.,
Color green per IPC-SM-840, class T, RoHS Compliant
LDI mask must be used to register tolerance.
Solder Mask to copper layer registration to be within 0.003 inches
8. Finish, all exposed Copper, both sides, after solder mask, to be Electroless Nickle Immersion Gold (Ni thickness typical 150 micro inches and Au 3-5 micro inches) in accordance with IPC-45529.
9. Silkscreen Both sides using white permanent ink.
Silkscreen to copper layer registration to be within 0.003 inches
10. Cut out according to mechanical layer 3 (cutout), Milling tool is to be 20 mil diameter.